# Product End-of-Life Disassembly Instructions

**Product Category:** Notebooks and Tablet PCs

**Marketing Name / Model**
[List multiple models if applicable.]

| HP ProBook 470 G2 Notebook PC |

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**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Mother board / Touch_PCB / Audio_PCB / Card Reader_PCB / HDD Transfer / ODD Transfer</td>
<td>6</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries Base battery and button battery</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps LCD</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>Power cable,adapter</td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
</tbody>
</table>
Components and waste containing asbestos

Components, parts and materials containing refractory ceramic fibers

Components, parts and materials containing radioactive substances

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screw driver</td>
<td>PH0x50</td>
</tr>
<tr>
<td>Screw driver</td>
<td>T8x40</td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove battery
2. Remove door
3. Remove HDD
4. Remove HDD bracket
5. Remove ODD
6. Remove keyboard
7. Remove log up assembly
8. Remove display assembly
9. Remove fan module
10. Remove DC-in cable
11. Remove MB assembly
12. Remove speaker module
13. Remove audio board assembly
14. Remove finger print assembly
15. Remove function board assembly
16. Remove power board assembly
17. Remove card reader assembly
18. Remove TP BTN assembly
19. Remove TP module
20. Remove AL skin
21. Remove KB support bracket
22. Remove LCD bezel
23. Remove panel
24. Remove hinge
25. Remove WLAN module
26. Remove camera module and cable
27. Remove HDD and ODD Transfer
28. Remove RAM module
29. Remove NGFF module
30. Remove mini card module
31. Remove thermal module
32. 

PSG instructions for this template are available at [EL-MF877-01](#)
3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

Step 1 Remove battery

Step 2 Remove door

Step 3 Remove HDD

Step 4 Remove HDD bracket

PSG instructions for this template are available at EL-MF877-01
Step 5 Remove ODD

Step 6 Remove keyboard

Step 7 Remove log up assembly

Step 8 Remove display assembly

Step 9 Remove fan module

Step 10 Remove DC-in cable

PSG instructions for this template are available at EL-MF877-01
Step 11 Remove MB assembly

Step 12 Remove speaker module

Step 13 Remove audio board assembly

Step 14 Remove finger print assembly

Step 15 Remove function board assembly

Step 16 Remove power board assembly

PSG instructions for this template are available at EL-MF877-01
Step 17 Remove card reader assembly

Step 18 Remove TP BTN assembly

Step 19 Remove TP module

Step 20 Remove AL skin

Step 21 Remove KB support bracket

Step 22 Remove LCD bezel
Step 23: Remove panel

Step 24: Remove hinge

Step 25: Remove WLAN module

Step 26: Remove camera module

Step 27: Remove HDD and ODD Transfer

Step 28: Remove RAM

PSG instructions for this template are available at EL-MF877-01
Step 29  Remove NGFF module

Step 30  Remove mini card module

Step 31  Remove thermal module